



DIMENSION	MIN.	NOM.	MAX.
A	2.05	2.28	2.56
A1	0.4	0.45	0.5
A2	1.15	1.28	1.41
A3	0.5 REF.		
b	0.5	-	0.7
D	6.0 BSC		
D1	5.1 BSC		
E	6.0 BSC		
E1	5.1 BSC		
e	0.85 BSC		
aaa	0.2		
bbb	0.25		
ddd	0.2		
eee	0.25		
fff	0.1		
N	24		

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
2. SYMBOL 'N' IS THE NUMBER OF BALLS AFTER DEPOPULATING.
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO PRIMARY DATUM C
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
6. MATERIAL MUST BE COMPLIANT WITH MAXIM SPECIFICATION 10-0131 FOR SUBSTANCE CONTENT, MUST BE Eu ROHS COMPLIANT WITHOUT EXEMPTION AND PB-FREE.
7. ALL DIMENSIONS APPLY TO PbfREE (+) PKG. CODE.
8. PACKAGE CODE: X2466MK+1



TITLE:
PACKAGE OUTLINE, 24 BALLS CERBGA,
6x6x2.82mm, 0.85mm PITCH

APPROVAL	DOCUMENT CONTROL NO. 21-100024	REV. A	1/1
----------	-----------------------------------	-----------	-----